



## Fatigue Life Prediction of Solder Joints in Electronic Packages with Ansys®

By Madenci, Erdogan / Guven, Ibrahim

Book Condition: New. Publisher/Verlag: Springer, Berlin | Fatigue Life Prediction of Solder Joints in Electronic Packages with ANSYS® describes the method in great detail starting from the theoretical basis. The reader is supplied with an add-on software package to ANSYS® that is designed for solder joint fatigue reliability analysis of electronic packages. Specific steps of the analysis method are discussed through examples without leaving any room for confusion. The add-on package along with the examples make it possible for an engineer with a working knowledge of ANSYS® to perform solder joint reliability analysis. Fatigue Life Prediction of Solder Joints in Electronic Packages with ANSYS® allows the engineers to conduct fatigue reliability analysis of solder joints in electronic packages. | Preface. List of Commands. List of Tables. List of Figures. 1: Introduction. 1.1. Numerical Modeling with Finite Element Analysis. 1.2. Constitutive Relations. 1.3. Failure Prediction. 1.4. References. 2: Thermomechanical Fatigue Life Prediction Analysis. 2.1. Approach. 2.2. Analysis Steps. 2.3. Case Study: BGA-Type Package. 2.4. References. 3: Mechanical Bending Fatigue Life Prediction Analysis. 3.1. Approach. 3.2. Analysis Steps. 3.3. Case Study: BGA-Type Package. 3.4. References. 4: Macro Reference Library. 4.1. Overview. 4.2. Preprocessor. 4.3. Solution. 4.4. Postprocessing. 4.5. References. Appendix A: Installation...

DOWNLOAD



READ ONLINE

[ 2.36 MB ]

### Reviews

*This type of book is everything and helped me seeking forward and a lot more. We have go through and so i am confident that i will planning to read again again later on. You will like just how the blogger create this ebook.*

-- Lilla Stehr

*Very good e book and useful one. it was actually written extremely properly and useful. I found out this pdf from my i and dad recommended this publication to discover.*

-- Heloise Wiegand